

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
30 June 2005 (30.06.2005)

PCT

(10) International Publication Number
WO 2005/059646 A3

(51) International Patent Classification⁷: **G03F 7/16**,
7/00, C11D 7/24, G03F 7/32

(21) International Application Number:
PCT/JP2004/018973

(22) International Filing Date:
14 December 2004 (14.12.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
2003-418112 16 December 2003 (16.12.2003) JP
60/532,715 29 December 2003 (29.12.2003) US

(71) Applicant (for all designated States except US): **SHOWA DENKO K.K.** [JP/JP]; 13-9, Shibadaimon 1-chome, Minato-ku, Tokyo 1058518 (JP).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **KANEDA, Masato** [JP/JP]; C/o Showa Denko K.K., 4980, Kaiseicho, Shunan-shi, Yamaguchi 7460006 (JP). **MIKAWA, Yasuhiro** [JP/JP]; C/o Showa Denko K.K., 4980, Kaiseicho, Shunan-shi, Yamaguchi 7460006 (JP). **SHIMIZU, Koji** [JP/JP]; C/o Showa Denko K.K., 4980, Kaiseicho, Shunan-shi, Yamaguchi 7460006 (JP).

(74) Agents: **AOKI, Atsushi** et al.; A. Aoki, Ishida & Associates, Toranomom 37 Mori Bldg., 5-1, Toranomom 3-chome, Minato-ku, Tokyo 1058423 (JP).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— with international search report

(88) Date of publication of the international search report:
30 March 2006

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: PHOTSENSITIVE COMPOSITION REMOVER

(57) Abstract: A photosensitive composition remover used for removal of an uncured photosensitive composition, which remover comprises 1 to 80 percent by mass of at least one type of aromatic hydrocarbon having 9 carbon atoms or more within the molecule. The photosensitive composition remover further comprises an aprotic polar solvent and/or another solvent other than aprotic polar solvents. The photosensitive composition remover is effective for removal of an uncured photosensitive composition film deposited at the periphery, edges, or back of a substrate or removal of an uncured photosensitive composition deposited at the surface of system members or equipment in a process for forming a photosensitive composition film on a glass substrate, a semiconductor wafer, or the like. It is preferably used for removal of a photosensitive composition containing a pigment in a process for forming a photosensitive composition film on a substrate in the process of production of a liquid crystal or an organic EL display.



WO 2005/059646 A3